1 Package summary

Terminal position code B (bottom)

Package type descriptive code PLLMC

Package style descriptive code PLLMC (plastic leadless module carrier)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 22-05-2006

Manufacturer package code 98ASA01308D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	8.1	-	mm
package width	-	5.15	-	mm
seated height	-	-	0.33	mm
nominal pitch	-	9.5	-	mm
actual quantity of termination	-	0	-	



NXP Semiconductors SOT500-2

plastic leadless module carrier package; 35 mm wide tape

2 Package outline

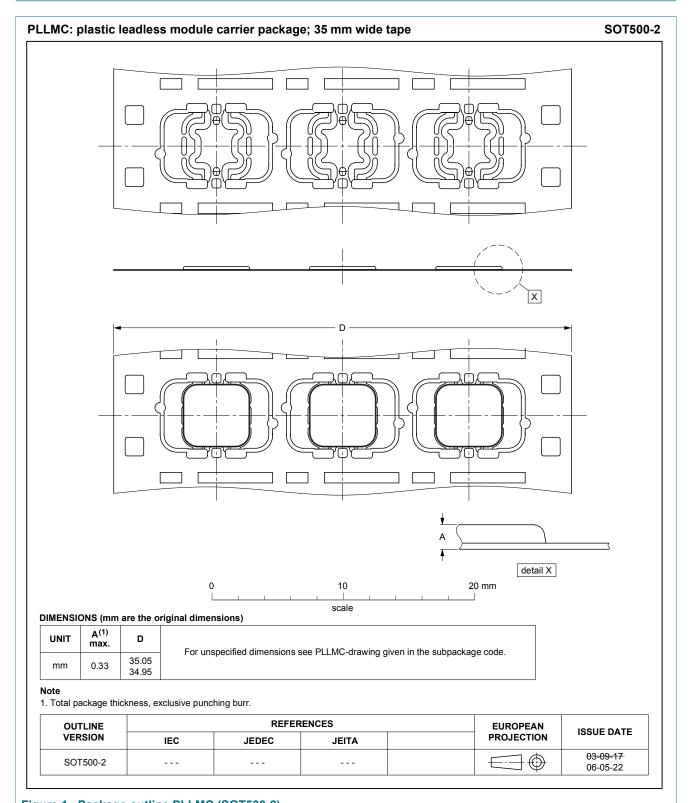


Figure 1. Package outline PLLMC (SOT500-2)

NXP Semiconductors SOT500-2

plastic leadless module carrier package; 35 mm wide tape

3 Legal information

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NXP Semiconductors SOT500-2

plastic leadless module carrier package; 35 mm wide tape

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